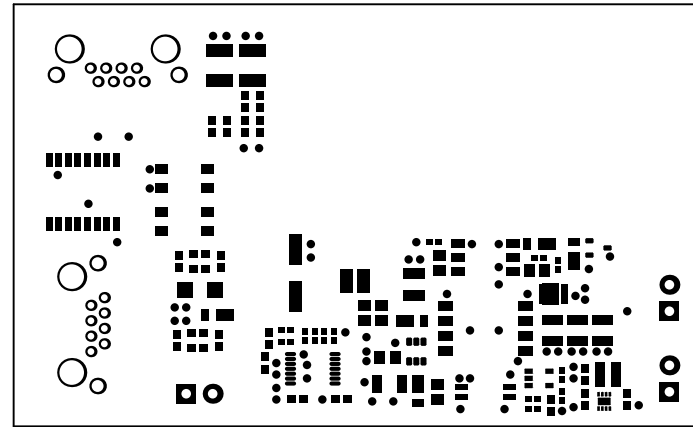
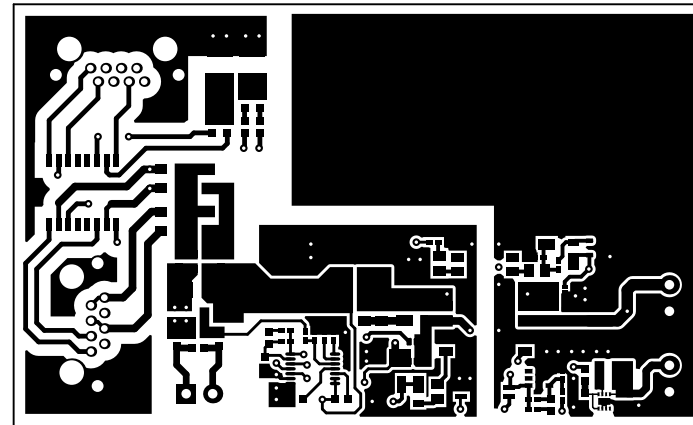


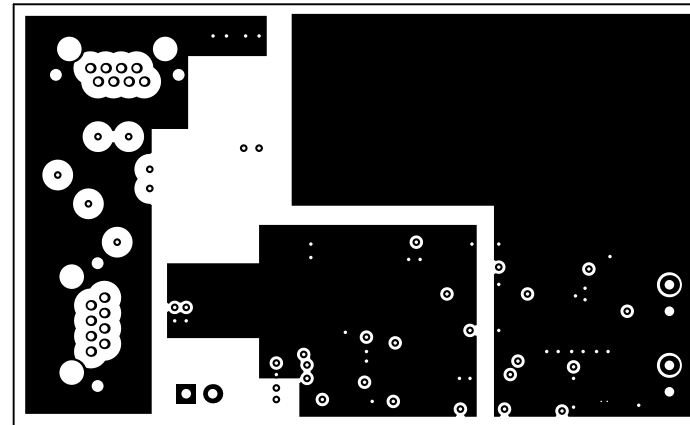
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 11/6/2017	11:05:08 AM	TEXAS INSTRUMENTS



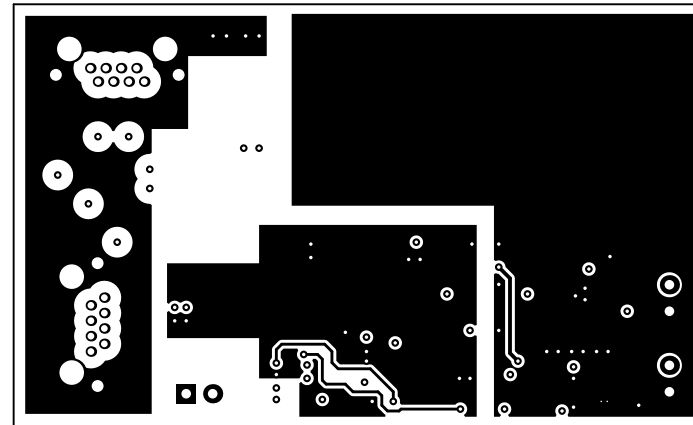
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 11/6/2017 11:05:08 AM	TEXAS INSTRUMENTS	



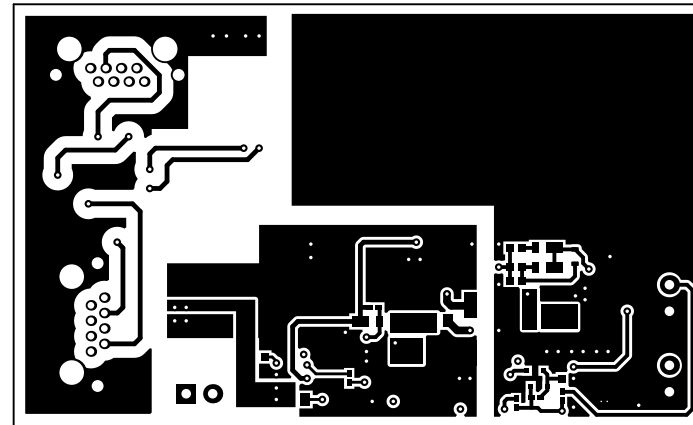
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 11/6/2017 11:05:09 AM	TEXAS INSTRUMENTS	



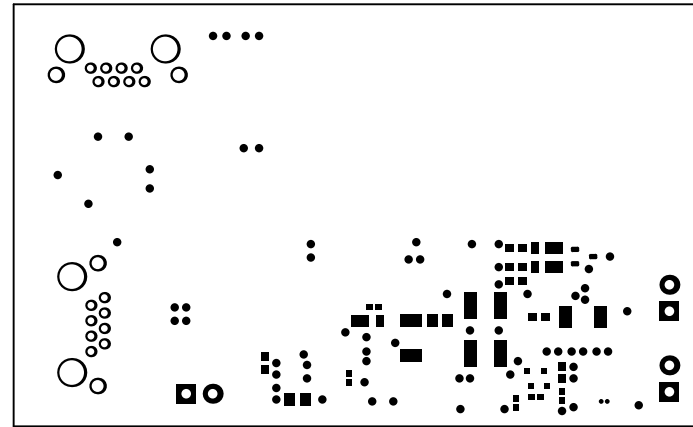
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 11/6/2017 11:05:10 AM	TEXAS INSTRUMENTS	



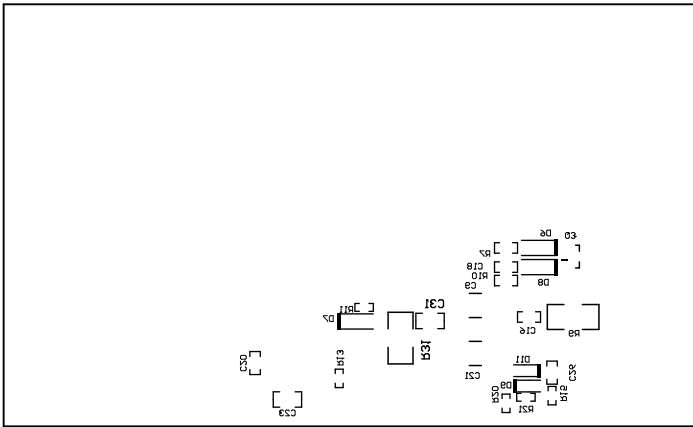
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 11/6/2017 11:05:11 AM	TEXAS INSTRUMENTS	



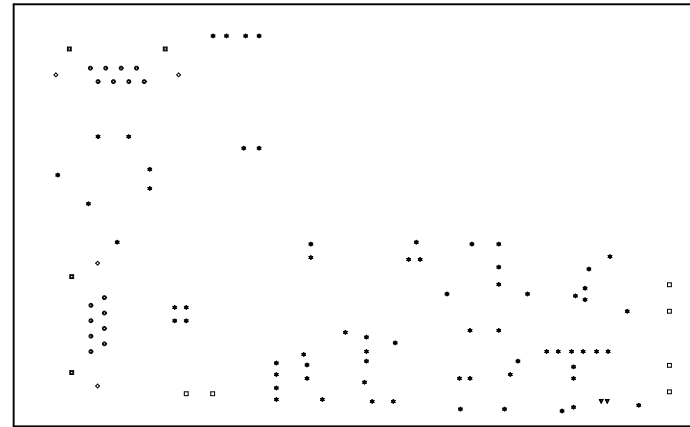
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 11/6/2017 11:05:11 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/6/2017 11:05:12 AM	TEXAS INSTRUMENTS	

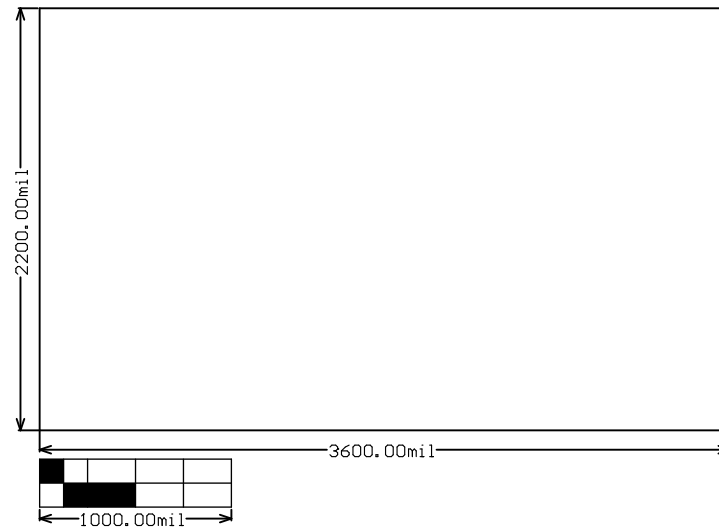


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 11/6/2017	11:05:13 AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▼	2	7.87mil (0.200mm)	PTH	Round
✱	69	18.00mil (0.457mm)	PTH	Round
●	16	35.04mil (0.890mm)	PTH	Round
□	6	50.00mil (1.270mm)	PTH	Round
◇	4	61.81mil (1.570mm)	PTH	Round
■	4	128.00mil (3.251mm)	PTH	Round
	101 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 11/6/2017	11:05:13 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11271	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 11/6/2017 11:05:14 AM	TEXAS INSTRUMENTS	

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